

**GAPFILL PROCESS USING A COMBINATION OF SPIN-ON-
GLASS DEPOSITION AND CHEMICAL VAPOR DEPOSITION
TECHNIQUES**

ABSTRACT OF THE DISCLOSURE

A method of filling a plurality of trenches etched in a substrate. In one embodiment the method includes depositing a layer of spin-on glass material over the substrate and into the plurality of trenches; exposing the layer of spin-on glass material to a solvent; curing the layer of spin-on glass material; and depositing a layer of silica glass over the cured spin-on glass layer using a chemical vapor deposition technique.

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